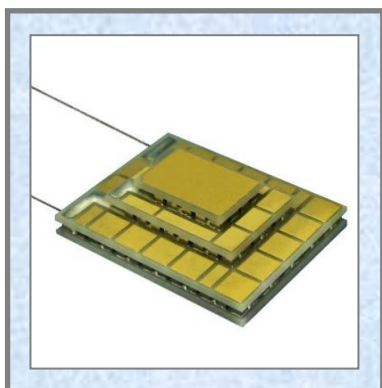


# THERMO MODULE DATA

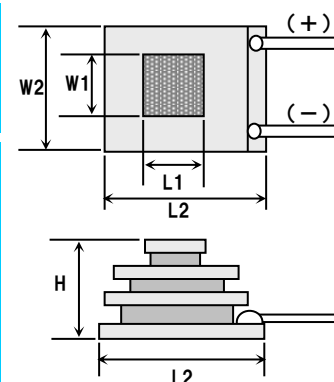
Model **K3MCO11** ( RoHS (EU) 2015/863 Compliant )



Th	$\Delta T_{max}(^{\circ}C)$	$I_{max}(A)$	$V_{max}(v)$	$Q_{cmax}(w)$
27°C	117	5.0	7.4	6.5
70°C	145	5.0	9.1	7.7

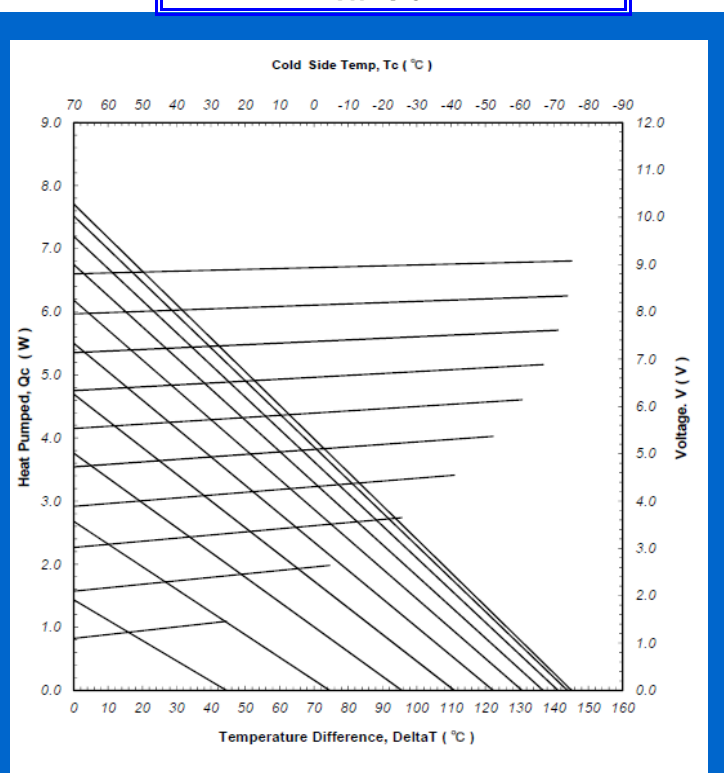
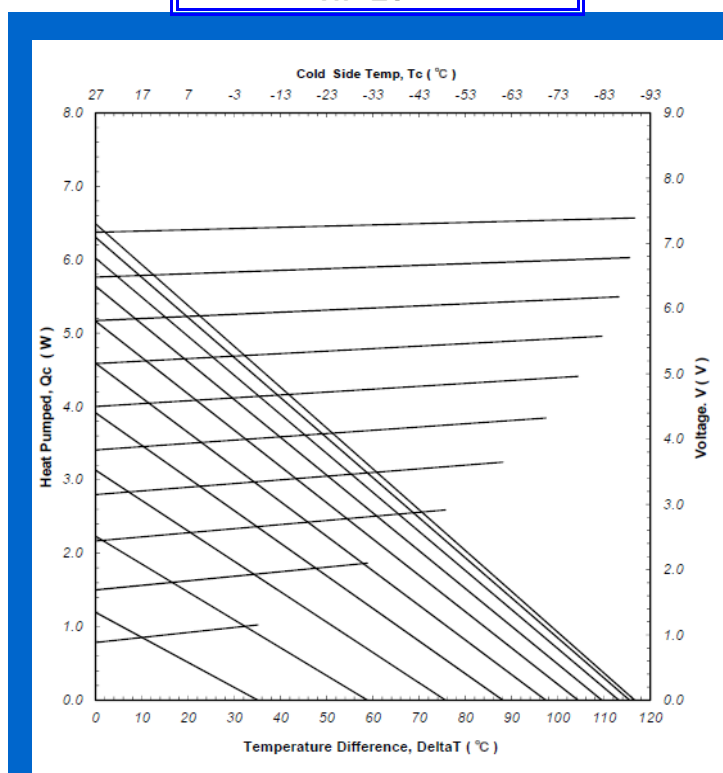
	W1	L1	W2	L2	H
Size(mm)	8.5	13.0	21.5	28.0	7.3
Tolerance(mm)	$\pm 0.1$	$\pm 0.1$	$\pm 0.2$	$\pm 0.2$	$\pm 0.4$
Metallization	Cu-Ni-Au				
Ceramic material	Aluminum nitride (AlN) <input type="checkbox"/>				
Assembly solder	SnAgCu (melting point : 217°C) <input type="checkbox"/>				



## Performance Diagram

Th=27°C

Th=70°C



Ambient Vacuum

Current value I = 0.5 - 5.0 A ( Step = 0.5 A )

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